

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1tc3108egn-1#trpbf

(Engineering Calculation)

SSOP

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**TOTAL MASS (g) : 0.078995**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000825	1000000	10443.6894531		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.029933	975000	378922.375		
		Iron (Fe)	7439-89-6	0.000737	24000	9329.69628906		
		Phosphorus (P)	7723-14-0	0.000009	300	113.931167603		
		Zinc (Zn)	7440-66-6	0.000021	700	265.839355469		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.030700</b>	<b>1000000</b>	<b>388631.84375</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.002272	1000000	28762.3027344		
		<b>External Plating Total:</b>				<b>0.002272</b>	<b>1000000</b>	<b>28762.3027344</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000246	1000000	3114.1184082		
		<b>Internal Plating Total:</b>				<b>0.000246</b>	<b>1000000</b>	<b>3114.1184082</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000407	750000	5152.22021484		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000136	250000	1721.62634277		
<b>Die Attach Total:</b>				<b>0.000543</b>	<b>1000000</b>	<b>6873.84667969</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.006623	150000	83840.671875		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.036203	820000	458294.40625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.001104	25000	13975.5556641		
		Carbon Black (C)	1333-86-4	0.000221	5000	2797.64282227		
		<b>Encapsulation Total:</b>				<b>0.044151</b>	<b>1000000</b>	<b>558908.3125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000258	1000000	3266.02636719		
					<b>TOTAL MASS (g) :</b>	<b>0.078995</b>		